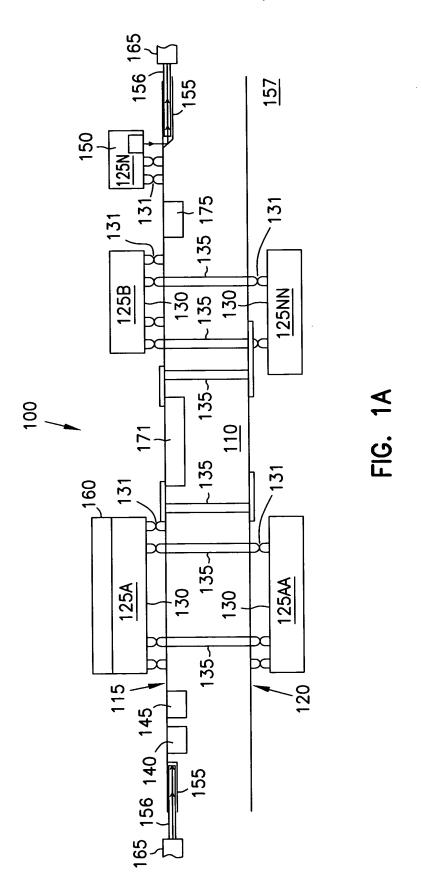
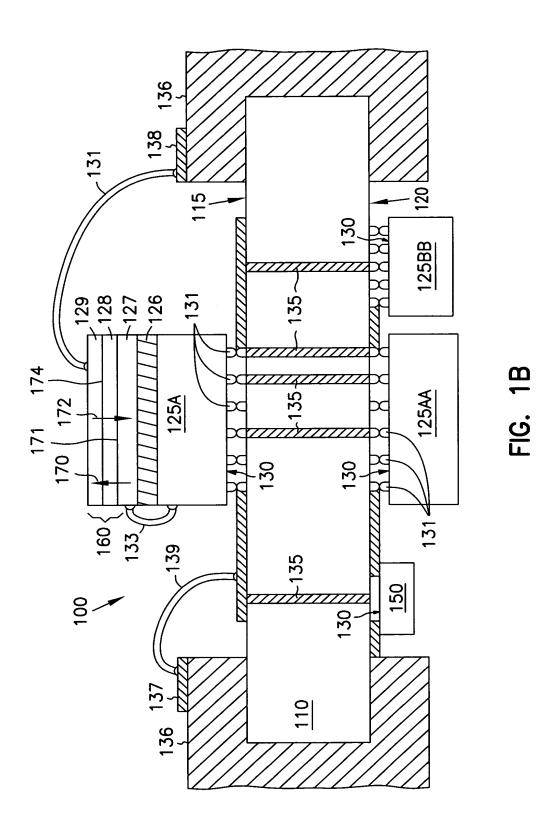
TITLE: COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC COOLING INVENTORS NAME: Kie Y. Ahn et al. DOCKET NO.: 303.533US2



DOCKET NO.: 303.533US2



DOCKET NO.: 303.533US2

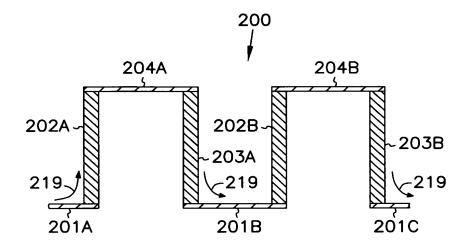


FIG. 2

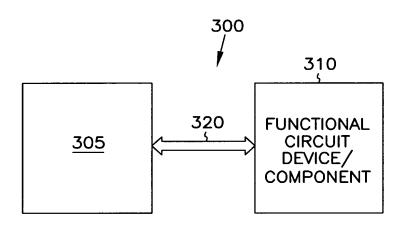
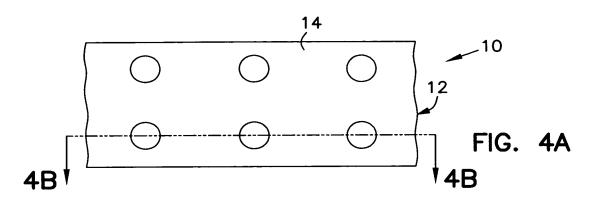
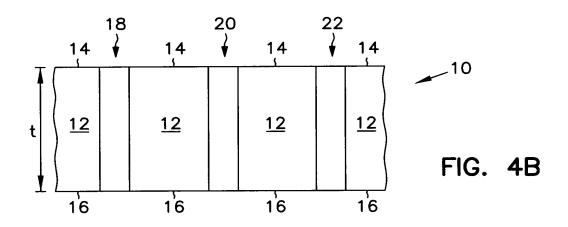


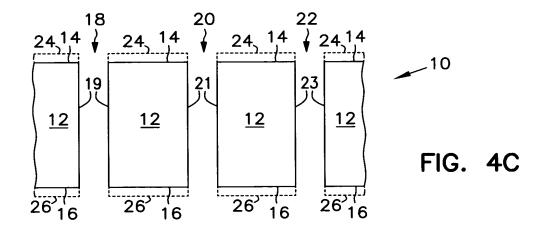
FIG. 3

DOCKET NO.: 303.533US2



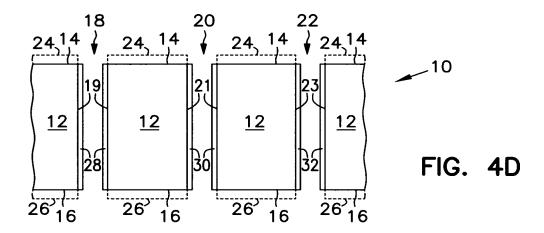


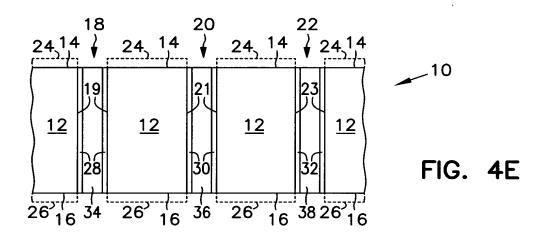




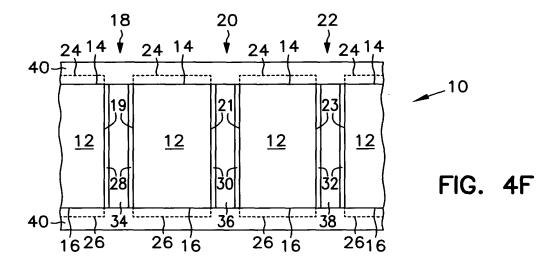
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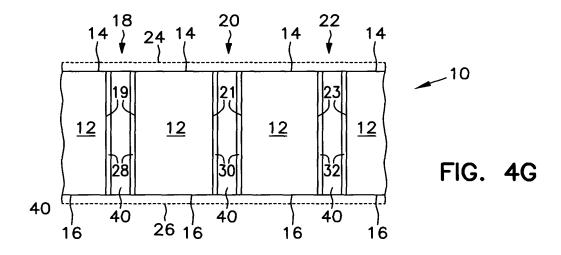
5/10





TITLE: COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC COOLING INVENTORS NAME: Kie Y. Ahn et al. DOCKET NO.: 303.533US2





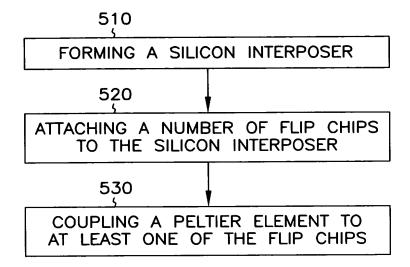


FIG. 5

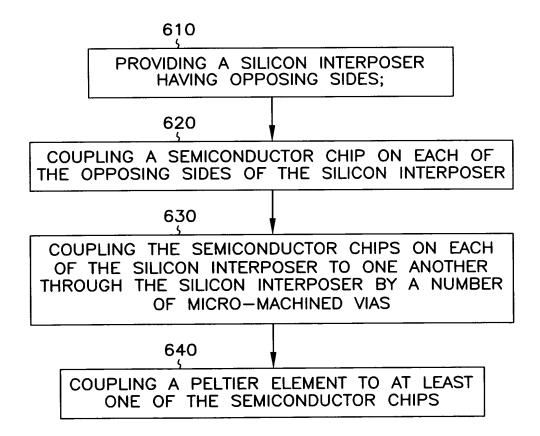


FIG. 6

DOCKET NO.: 303.533US2

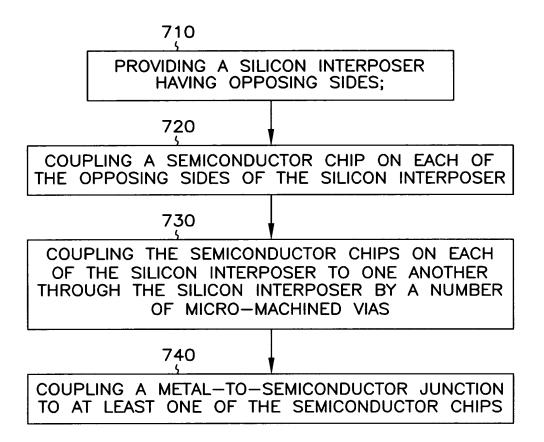


FIG. 7

DOCKET NO.: 303.533US2

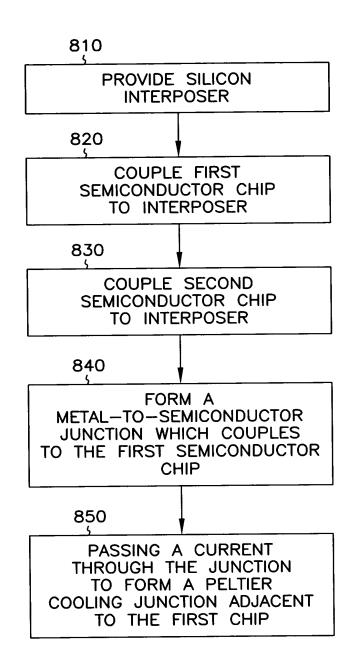


FIG. 8

TITLE: COMPACT SYSTEM MODULE WITH BUILT-IN THERMOELECTRIC COOLING

INVENTORS NAME: Kie Y. Ahn et al. DOCKET NO.: 303.533US2

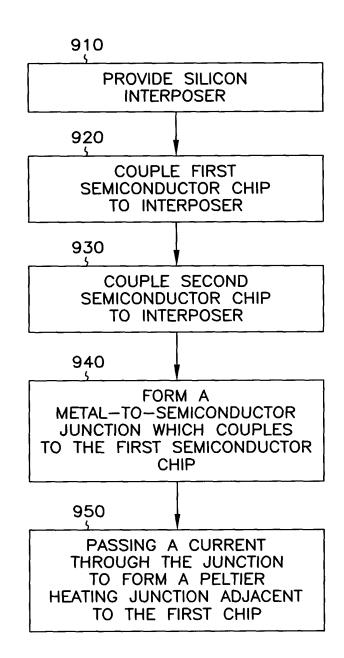


FIG. 9